

ADVANCE PROGRAM

PICALO General Conference Chair: Minlin Zhong, Tsinghua University, Beijing, People's Republic of China

PICALO Laser Materials Processing Conference Chairs:

Lin Li, The University of Manchester, Manchester, UK **Hau-Chung Man,** The Hong Kong Polytechnic University, Hung Hom, Kowloon, Hong Kong

PICALO Micro, Nano & Ultrafast Fabrication Conference Chairs:

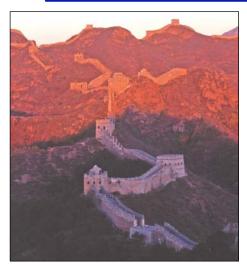
Yongfeng Lu, University of Nebraska-Lincoln, Lincoln, NE, USA **Xiaoyan Zeng**, Huazhong University of Science & Technology, Wuhan, People's Republic of China

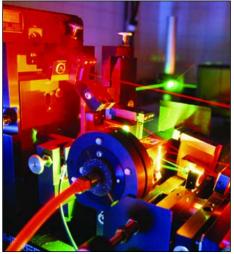
PICALO International Enterprise Summit - NEW FOR 2008!

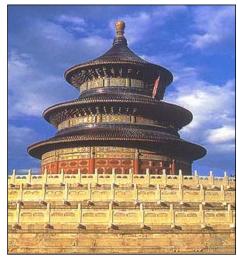
Globalization: Opportunities & Challenges for Laser Companies in China & the World

Bo Gu, GSI Group, Inc., Wilmington, MA, USA

Rangda Wu, Chutianlaser, Wuhan, People's Republic of China







FEATURING

Laser Materials Processing Conference

Micro, Nano & Ultrafast Fabrication Conference

PICALO International Enterprise Summit - NEW FOR 2008! Globalization: Opportunities & Challenges for Laser Companies in China & the World

> Presented by Laser Institute of America in cooperation with Laser Processing Committee of China Optical Society (LPC-COS) and Tsinghua University







PICALO 2008 Conference Agenda

Sunday, April 13 - Monday, April 14

Pre-Conference Wuhan Tour

Wednesday, April 16

8:00am Registration Desk Open

9:00am Plenary Session

12:00pm Lunch in Local Restaurant

1:30pm LMP #1: Laser Cutting & Machining

LMP #2: Surface Modification LMP #3: Laser Welding & Joining I Micro #1: Fundamental Science in Laser-Material Interactions

2:50pm Afternoon Break

3:10pm Micro #2: Near-Field Phenomena for

Nanoprocessing

5:00pm Welcome Reception

Thursday, April 17

8:00am Registration Desk Open

9:00am LMP #4: Industrial Applications I

Micro #3: Laser Microfabrication in Industry Micro #4: Laser Assisted Device Fabrication Laser Materials Processing Poster Presentation

Gallery

10:20am Morning Break

10:40am Micro #5: Laser Microwelding

Micro #6: Laser Direct Writing

12:00pm Lunch in Local Restaurant

1:30pm LMP #5: Additive Manufacturing

LMP #6: Laser Welding & Joining II Micro #7: Ultrafast Processes in Materials

Processing

International Enterprise Summit

2:50pm Afternoon Break

3:10pm Micro #8: Laser Microprocessing for Photonic

Devices

5:30pm Vendor TableTop Display & Reception

Friday, April 18

8:00am Registration Desk Open

9:00am LMP #7: Hybrid Welding & Joining

LMP #8: Modeling & Simulation LMP #9: Lasers & Systems

Micro #9: Lasers in Bio-engineering Micro, Nano & Ultrafast Fabrication Poster

Presentation Gallery

10:20am Morning Break

10:40am Micro #10: Laser Micromachining

12:00pm Lunch in Local Restaurant

1:30pm LMP #10: Industrial Applications II

LMP #11: Laser Drilling, Forming, &

Peening

LMP #12: Laser Surface Modification

Micro #11: Laser Synthesis & Sintering of

Nanoparticles

2:50pm Afternoon Break

3:10pm Micro #12: Advanced Laser Applications

6:00pm Closing Banquet

Saturday, April 19

Post Conference Tour – Great Wall of China

Special Thanks to the PICALO 2008 Cooperating Societies

Association of Laser Users

Beijing Optical Society

Chinese Journal of Lasers

Chinese Society of Non-Traditional Machining

Chinese Welding Society

European Laser Institute

European Optical Society

Japan Laser Processing Society

^{*}Program subject to minor changes

PICALO 2008 Conference Chair Welcome



Minlin Zhong Tsinghua University Beijing, People's Republic of China

Welcome to PICALO 2008 and Beijing - "The Olympics" for international laser materials processing. PICALO 2008 is the third conference focusing on the growth of industrial lasers and applications in the pacific region. The general aim of PICALO is to bring together researchers, engineers, equipment suppliers and industry personnel to hear the latest developments and progress in lasers and applications and to share knowledge, experiences and visions. PICALO 2008 will feature an exciting laser macro/micro processing program, a unique international enterprise summit and a charming post-conference excursion in Beijing. You will feel the rapid development of the country, the fantastic Chinese culture and long history, the dynamic and modern metropolitan activities and also the Olympic atmosphere -one world, one dream!

of China The organizing committee will ensure that you get the maximum benefit from the technical program while having a great time during the conference. I would encourage you to take this opportunity to spend time here and enjoy this great country, her great culture, the Great Wall and the delicious Chinese food. PICALO 2008 is presented by Laser Institute of America in cooperation with the Laser Processing Committee of China Optical Society (LPCCOS) and Tsinghua University. LIA will handle all abstract submissions and conference registrations. On behalf of the organizing committee and conference chairs, I would like to formally invite you to attend PICALO in April 2008 in Beijing and be a part of this great event!

Minlin Zhong

Plenary Session

Extreme Photonic/Laser Processing: Ultra Intense, Ultra-fast & Nano-scale

PICALO 2008 can be called the Olympics for Laser Materials Processing as it will be held in Beijing, the 2008 Olympic host city. "To be higher, stronger and faster" challenges humans to their utmost. Likewise, laser applications have been continuously pushed forward to almost every aspect of science and engineering and to almost every extent of possibility. The PICALO 2008 plenary session highlights "extreme photonic/laser processing," characterizing extreme high power intensity, extreme short pulse duration and extreme new material and phenomena. This plenary session starts with an impressive report on 150-terawatt power laser-mater relativistic interaction, generation of bright pulses of energetic (keV - MeV) x-rays and charged-particle beams, and unique applications in the physical sciences, biomedicine, defense and homeland security. Follows is an intriguing presentation on Photonic Meta Materials, Nano-scale plasmonics and Super Lens, which may inspire profound impact in wide range of applications such as nano-scale imaging, nanolithography, and integrated nano photonics. The session continues with an interesting report on state-of-the-art high power high brightness laser materials processing with characteristic traits on smaller, cost-effective and processing on-the-fly. The session also highlights a research and development work on a made-in-China 8 kW diode pumped solid state laser and its applications.

Invited Plenary Speakers

Ultra-intense Laser-matter Interactions with a 150-terawatt Power Laser

 $\textbf{Donald Umstadter,} \ University \ of \ Nebraska-Lincoln$

Photonic Meta Materials, Nano-scale Plasmonics and Super Lens

Zhang Xiang, UC Berkeley

High Power Laser Materials Processing -New Developments and Trends

Eckhard Beyer, Frauhofer IWS

Research and Development on High Power DPSSL in China

Jinmin Li, Institute of Semiconductor, Chinese Academy of Sciences

About Laser Institute of America

Laser Institute of America (LIA) is the international society for laser applications and safety. LIA's mission is to foster lasers, laser applications, and laser safety worldwide. Serving the industrial, medical, research and government communities, LIA offers technical information and networking opportunities to laser users from around the globe.

LIA presents several conferences that are recognized by the global community to be the best forums for exchanging up-to-date technical information on laser technology, applications, and safety. Attracting the best minds from the hottest fields, these forums bring together laser professionals from North America, Europe, Asia, and the Pacific Rim.

LIA also offers a wide array of products and services to thousands of end users. These include safety and applications publications, training videos, signs and labels, Laser Safety Officer training, and more. For more information, visit LIA at www.laserinstitute.org.

PICALO Tours

PICALO Pre-Conference Laser Industry Tour Wuhan, China

Sunday, April 13 - Monday, April 14

PICALO attendees have the opportunity to visit historic Wuhan and tour prominent laser companies.

Cost: \$150USD per participant

Additional to PICALO registration fee; air travel arrangements on own.

Wuhan, capital of the Hubei province, is known as China's Optical Valley. It is the largest base for the optical electronics and photoelectronics industries in China. The Optical Valley is located in the Wuhan East Lake High-Tech development zone. Wuhan's optical electronics industry encompasses optical communication, power and consumer optical electronics, and relevant software. The industry is on an upswing, with the production value growing by an average of 30 percent a year since 2001. Its fiber-optic cable sector is currently third in the world in terms of manufacturing capability.

Participants who arrive Sunday evening will enjoy dinner and a Yangtze River Evening Cruise. The tour on Monday will feature three companies (National Optical-electronic Laboratory, Huazhong Univ. of Science and Technology, Chutian Laser Processing Company and Huagong Laser Engineering Company), and attendees will interact with executives from each company. Enjoy a driving tour of Wuhan and see the history including including Huanghe Pagoda and East Lake. Conclude the day with a closing dinner banquet including representatives from the featured companies and other area Wuhan laser companies. Don't miss this exciting networking opportunity in Wuhan, China!

See complete itinerary at www.laserinstitute.org/conferences/picalo.

PICALO Post Conference Tour: MutianYu Section of the Great Wall of China, Ming Tombs, & the Famous Cloisonné Factory

Saturday, April 19

Cost: \$110USD per participant (additional to PICALO registration fee) Includes roundtrip transportation from the Capital Hotel, lunch, all admission fees and gratuities.

The Great Wall

An hour's drive from Beijing's center is an amazing work of architectural innovation, the Great Wall of China. The Great Wall, the only man made wonder of the ancient world which can be seen from the moon, is a magnificent monument to China's long and rich history.

The PICALO tour will visit a lesser know section of the Wall - MutianYu. Located at Huairou County some 73 kilometers (about 45 miles) northeast of the Beijing urban area, MutianYu Great Wall winds along lofty, cragged mountains from the southeast to the northwest for approximately 2.25 kilometers (about 1.4 miles). Connected with Juyongguan Pass to the west and Gubeikou to the east, this section of the Great Wall holds a prominent place in Chinese military history. Take time to walk up the snaking sections of walls, peek through the watchtowers and enjoy the amazing view.



Participants will have plenty of time to marvel at the sites (approximately 3 hours). Depart the Great Wall and head to lunch at a Chinese style restaurant (included in tour fee).

Depart after Lunch for the Ming Tombs via the "Sacred Way."

Entrance to Ming Tombs at the Sacred Way

The Ming dynasty was known as the "period of restoration and reorganization" in the 18th century as China, under the Ming era, saw a flourish of the trading business with the rest of the world. With that prosperity, the wealth was splurged on both the living and the dead.

Take a tour of the vast mausoleums of 13 emperors of the Ming Dynasty at the Ming Tombs which lie northwest of Beijing. After taking in the Great Wall (which the Ming emperors were heavily involved in), venture around the magnificent Changling tomb which inhumes Emperor Zhuli and his empresses, some of which were said to be buried alive.

Cloisonné Factory Visit

End the day with a visit to a cloisonné factory. Cloisonné is a unique combination of copper and porcelain working skills, traditional painting, sculpting, and etching skills. Originating in Beijing during the Yuan Dynasty (1271-1368), Cloisonné is an intricate process that requires many years of training for an artisan to master. Cloisonné pieces can be found in large objects, such as vases and other large utensils and decorative items, as well as small items like earrings, bracelets, chopsticks, or jars.

Laser Materials Processing Conference



Lin Li
The University of
Manchester
Manchester, UK



Hau-Chung Man The Hong Kong Polytechnic University Hung Hom, Kowloon, Hong Kong

Comesaña, Univ. de Vigo

The PICALO Laser Materials Processing Conference features the latest developments across the world in laser cutting / machining (metals, ceramics and glass, thick section), surface modification (marking, texturing, cladding, sintering, cold spray, melt injection, induction assisted cladding, laser-sol coating, combined cladding/shot peening), welding (alloys, plastics, fibre laser welding, welding dissimilar materials, hybrid welding), additive manufacturing (selective laser melting, direct laser deposition), lasers and systems (fibre laser, diode laser, CO2 laser, process sensing and control), modelling and simulation (fluid dynamics, temperature fields, FE and analytical modelling), drilling and forming, and industrial applications (aerospace, automotive, petroleum, energy, bio-medical and process industries). The presentations are given in 10 oral sessions with over 80 papers and a poster session. Invited speakers from leading research groups and companies worldwide are presenting their recent findings and future prospects.

A special characteristic of the conference is the large number of participants from Asia, especially from China,

providing an opportunity for the laser manufacturers, equipment suppliers as well as various industries and academics for the exploration of commercial and academic collaborations and businesses.

LMP Session 1: Laser Cutting & Machining Wednesday, April 16 • 1:30pm

Session Chair: Duncan Hand, Heriot-Watt Univ., Edinburgh, UK

Current Challenges to Laser Cutting Application (Invited Paper)...(101)
Takeji Arai, The Japan Society of Laser Technology

Reactive Thick Section Cutting with Fibre and Disk Laser...... (103)William O'Neill, Tao Zhang, Univ. of Cambridge

Laser Machining in Ceramics Manufacture (Invited Paper).....(105)Duncan Hand, Heriot-Watt Univ.

Chen, Geniray Technology Corporation

The Development of Laser-Chemical Combined Large Scale Etching on

> LMP Session 2: Surface Modification Wednesday, April 16 • 1:30pm

Session Co-chairs: Hau-Chung Man, The Hong Kong Polytechnic Univ., Hung Hom, Kowloon, Hong Kong; Minlin Zhong, Tsinghua Univ., Beijing, People's Republic of China

A New Method of Laser Beam Induced Surface Modification using the Surfi-Sculpt® Process (Invited Paper) (201) Paul Hilton, TWI Ltd.

Program Committee:

Pascal Aubry, CEA / GERAILP, Arcueil, France Woong-Seong Chang, RIST, Pohang, South Korea Yanbin Chen, Harbin Institute of Technology, Harbin, People's Republic of China

Paul Hilton, TWI Ltd., Great Abington, Cambridge, UK Weidong Huang, Northwestern Polytechnic Univ., Xian, People's Republic of China

Takashi Ishide, Mitsubishi Heavy Industries, Ltd., Takasago, Hyogo, Japan

Stefan Kaierle, Fraunhofer ILT, Aachen, Germany **Seiji Katayama**, Osaka Univ., Ibaraki, Osaka, Japan **David Low,** SIMTech, Singapore

Henry Peng, GE (China) Research & Development Center Co. Ltd., Shanghai, People's Republic of China

G. Sundararajan, International Advanced Research Centre for Powder Metallurgy and New Materials, Andhra Pradesh, India **Kenneth Watkins,** The Univ. of Liverpool, Liverpool, UK **Lijue Xue,** National Research Council Canada, London, ON,

Y. Lawrence Yao, Columbia Univ., New York, NY, USA **Qingmao Zhang,** South China Normal Univ., Guangzhou, People's Republic of China

Yongkang Zhang, Jiangsu Univ., Zhenjiang, People's Republic of China

Norman Zhou, Univ. of Waterloo, Waterloo, ON, Canada **Xiao Zhu,** HUST, Wuhan, People's Republic of China

Surface Modification of Dental Hard Tissues using Pulsed UV Lasers (Invited Paper).....(205)
Victor Oliveira, Rui Vilar, Instituto Superior Técnico

Numerical and Experimental Investigation of Thermal Stresses and

Distortions in the Induction Assisted Laser Cladding............. (206)Frank Brückner, Dietrich Lepski, Fraunhofer IWS; Eckhard Beyer,
Fraunhofer IWS, Dresden Univ. of Technology

Manchester
A Novel Approach of Surface Modification by Means of Laser Cladding

> LMP Session 3: Laser Welding & Joining I Wednesday, April 16 • 1:30pm

Session Co-chairs: Yanbin Chen, Harbin Institute of Technology, Harbin, People's Republic of China; Paul Hilton, TWI Ltd., Cambridge, UK

Welding Performance of a 2KW Continuous Wave Supermodulated Nd:YAG Laser-increased Weld Speed, Weld Penetration and Reduced Porosity with Supermodulated Output Power.....(303)

Mohammed Naeem, GSI Group, Inc. - Laser Division

Failure Study on DP and HSLA Steels in Formability Testing (304) M. Xia, Norman Zhou, Univ. of Waterloo; Z. Tian, Central Iron & Steel Research Institute Laser Welding of Aeronautic Titanium Alloys (Invited Paper) (305) Shui-li Gong, Wang Hong, BAMTRI Laser Welding of Ultra High Strength Steels for Automotive Applications	Innovative Laser Consolidation Process for Making Net-Shape Functional Components for Various Industrial Applications (Invited Paper)
LMP Session 4: Industrial Applications I Thursday, April 17 • 9:00am	Session Co-chairs: Dirk Petring, Fraunhofer ILT, Aachen, Germany; Andrew Pinkerton, The Univ. of Manchester, Manchester, UK Fibre Laser Welding of Ti6Al4V(601)
Session Co-chairs: Jack Gabzdyl, SPI Lasers, Southampton, UK; Lin Li, The Univ. of Manchester, Manchester, UK Advancement in Laser Drilling for Aerospace Gas Turbines (401) Mohammed Naeem, GSI Group, Inc Laser Division Experience-industrial Laser Surfacing Applications (402) Trevor Anderson, Jarvie Engineering Pty. Ltd. Challenges and Opportunities of Laser Rock Drilling for Petroleum	Jongkol Iammi, The Univ. of Nottingham Dissimilar Metal Welding Titanium and Steel Sheet by Fiber Laser
Industry Applications	Studies on the Pulsed Nd:YAG Laser Spot Welding of Magnet/Steel Dissimilar Materials
Manufacture and Repair of Aero Engine Components using Laser Technology (Invited Paper)(405) Ingomar Kelbassa, Fraunhofer ILT Automated Diodologor based Proving of Carbide Tipe for Optimized	Penetration Laser Welding
Automated, Diodelaser-based Brazing of Carbide Tips for Optimised Saw Blade Fabrication	Study of Laser Welding of Zinc Coated Sheet Steel in Overlap Configuration
Laser-assisted Production of Bioceramic Coatings from Marine Wastes	Experimental Approach in Warm Forming
LMP Session 5: Additive Manufacturing Thursday, April 17 • 1:30pm	Dissimilar Stainless Steels
Session Co-chairs: Milan Brandt, Swinburne Univ. of Technology, Melbourne, Australia; Lijue Xue, National Research Council of Canada, London, ON, Canada	LMP Session 7: Hybrid Welding & Joining Friday, April 18 • 9:00am
Analysis of the Powder Bed Laser Melting Process for Direct Manufacturing of Metallic Components (Invited Paper)	Session Co-chairs: Session Co-chairs: Steve Shi, TWI Ltd, Cambridge, UK; Norman Zhou, Univ. of Waterloo, Waterloo, ON, Canada Studies on the Effects of Welding Parameters on Temperature Fields in Laser-Plasma Arc Hybrid Welding of an Al-Li Alloy

Joining of Magnesium using Laser Assisted Self-pierce Riveting Technology	Process Control on Laser Cladding by Coaxial Vision for Direct Manufacturing of 3D Metallic Structures
LMP Session 8: Modeling & Simulation Friday, April 18 • 9:00am	Technology
Session Co-chairs: Rémy Fabbro, LALP (CNRS)/GIP GERAILP, Arcueil Cedex, France; Weidong Huang, Northwestern Polytechnic Univ., Xian, People's Republic of China	Reconditioning of Workpieces and Turbine Parts by Laser Metal Deposition of High Temperature Steels and Alloys
Research on Fluid Dynamics during Laser Deep Penetration Welding(801) Wang Hong, BAMTRI	The Application Research on Laser Welding Cab-roof of Truck(1003) Yuan Yao, China FAW Group Corp. R & D Center
Therotical and Experimental Research on Temperature Field of Coaxial Powder Flow in Laser Cladding(802) Yang Xichen, Laser Processing Center, Tianjin Polytechnic Univ.	Integrated Heat Treatment - Comparison of Different Machine Concepts
Integrated Model of Turbulent Fluid Flow, Heat Transfer and Mass Transfer in Laser Cladding Process for Direct Metal Deposition (803) Yanlu Huang, Yongqiang Yang, Guoqiang Wei, South China Univ. of Technology	Laser Material Processing in the Aero Engine Industry. Established, Cutting-Edge and Emerging Applications (1005) Karl-Hermann Richter, MTU Aero Engines
Modeling Utility for Percussion Laser Drilling - Experiment vs Theory. (804) Tom Eppes, Univ. of Hartford	Model-making of Building & Sculpture Based on Laser Rapid Prototyping Technology
Heat Transfer and Fluid Flow during Double-track Laser Cladding of H13 Tool Steel (Invited Paper)	Nopaltzin Li: The New Laser Machine for Cactus Cleaning with Optical Detection of Spines
Three-dimensional Analytical and Finite Element Methods for Simulating a Moving Melt Pool with Mass Addition (806) Andrew Pinkerton, Alhaji Kamara, Kamran Shah, Lin Li, The Univ. of Manchester	LMP Session 11: Laser Drilling, Forming, & Peening Friday, April 18 • 1:30pm
3D Finite Element Simulation for the Temperature Field of Direct Metal Laser Sintering Process(807) Xia Ji, Jiangsu Univ.	Session Co-chairs: Mohammed Naeem, GSI Group, Inc Laser Division, Rugby, UK; John Powell, Luleå Univ. of Technology, Luleå, Sweden
The Absorptance of Metal Surfaces to Nd:YAG/Nd:YLF Laser Light (808) D. Bergstrom, Mid Sweden Univ.; John Powell, Alexander Kaplan, Luleå Univ. of Technology	A Novel Hole Geometry Measurement Technique using a Laser Microbeam
LMP Session 9: Lasers & Systems Friday, April 18 • 9:00am	A Statistical Model for Research on the Focal Position Effect on the Taper of Laser Drilling
Session Co-chairs: Stefan Kaierle, Fraunhofer ILT, Aachen, Germany; Bill Shiner, IPG Photonics Corp., Oxford, MA, USA	Laser Drilling in Superalloy with 150~550Ns Pulses Train (1103) Zhang Xiaobing, BAMTRI
Advances of Fiber Lasers and their Applications (Invited Paper) (901) Bill Shiner, IPG Photonics Corp.	Topographic Analysis of Holes Drilled by Pulsed Nd:YAG Laser on DD6 Single-crystal Superalloy(1104)
The Design Method of High-efficiency Coupling of Fiber for the High- power Solid Laser	Chen Changjun, Zhang Min, Zhang Shichang, Chang Qingming, Yan Wenqing, Key Laboratory for Ferrous Metallurgy and Resources Utilization of Ministry of Education, Laser Processing Research Center; Zhang Xiaobing, Key Laboratory for High Energy Density Beam Processing Technology
Reliable High-power Laser Diode Arrays(903) Brad Debok, Ryan Feeler, Northrop Grumman Cutting Edge Optronics	Analysis of the Formability of Aluminum Alloy Sheet based on Laser Shock Forming
New Developments in CO2 Laser Technology Enable New Applications	Yinfang Jiang, Yongkang Zhang, Zhiwei Du, Runa Li, Chaoyang Shi, Jiangsu Univ.; Yuanyou Zhu, Nanjing Institute of Technology
Does High Beam Quality of Solid State Lasers Enhance Laser Material Processing? (Invited Paper)	Process Parameters Study of Closed-loop Laser Rapid Forming (1106) Jun Yu, Jing Chen, Hua Tan, Xin Lin, Weidong Huang, State Key Laboratory of Solidification Processing, Northwestern Polytechnical Univ.

The Study on the Laser Compound Forming of Sheet Metal (1107) YiBin Chen, Jianzhong Zhou, Jiangsu Univ.
The Fatigue Properties of Laser Shock Processed Aluminum Alloy 7050
Dynamical Simulation and Experimental Study on the Process of Laser Peen Forming of Metal Plate

LMP Session 12: Laser Surface Modification Friday, April 18 • 1:30pm

Session Co-chairs: Yijian Jiang, Institute of Laser Engineering, Beijing Univ. of Technology, Beijing, People's Republic of China; Rui Vilar, Instituto Superior Técnico, Lisboa Codex, Portugal

Imp	roving	Physic	cal Pr	opert	ies o	of Fun	ictio	nal Mate	erials	by L	aser
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Recent Developments of the Laser-assisted Cold Spray Process and

Matthew Bray, Andrew Cockburn, William O'Neill, Univ. of Cambridge

Mechanism Analysis on Dry-friction Abrasive Wear Resistance of Particulate Reinforced MMC Coatings by Laser Deposition for Corrugate Rollers
Metal Matrix Nano H-BN Self-lubricating Composite Coating Synthesized by Nd:YAG Laser Cladding(1205) A.H. Wang, Huazhong Univ. of Science and Technology
Study on the Deposition of Nickel Base Waspaloy Powder via High Power Fiber Laser
Laser Melt Injection of Monocrystalline WC Particles into Ti-6Al-4V
Residual Stress Distribution in Laser Alloying Zone with Fecsib Powder

Special Thanks To Our PICALO **International Advisory Board**

Eckhard Bever, Fraunhofer IWS, Dresden Univ. of Technology, Dresden, Germany

Milan Brandt, Swinburne Univ. of Technology, Melbourne, Australia

Friedrich Dausinger, Institut für Strahlwerkzeuge, Stuttgart, Germany

Shusen Deng, Laser Processing Committee of China Optical Society, Beijing, People's Republic of China

Walter W. Duley, Univ. of Waterloo, Waterloo, ON, Canada

Yuanzhong Lei, National Science Foundation of China, People's Republic of China

Gnian Cher Lim, Singapore Institute of Manufacturing Technology, Singapore

Wenjin Liu, Tsinghua Univ., Beijing, People's Republic of

Jyoti Mazumder, CLAIM, The Univ. of Michigan, Ann Arbor, MI, USA

Reinhart Poprawe, Fraunhofer ILT, Aachen, Germany

John Powell, Laser Expertise Ltd., Nottingham, UK

Chris Smallbone, Welding Technology Institute of Australia, Silverwater, Australia

William M. Steen, The Univ. of Liverpool, Liverpool, UK

Maocai Wang, Institute of Metal Research, Chinese Academy of Sciences, Shenyang, People's Republic of China

XiChen Yang, Tianjin Polytechnic Univ., Tianjin, People's Republic of China

Tiechuan Zuo, Beijing Univ. of Technology, Beijing, People's Republic of China

Laser Industry Vendor Program Reception & TableTop Display

Thursday, April 17 • 5:30pm

The Laser Industry Vendor Program gives vendors and conference attendees the opportunity to discuss equipment and applications in a relaxed setting. After completion of the technical sessions, share refreshments and product ideas with your colleagues and suppliers! Limited space is still available! For more information on participating as a vendor, contact Beth Cohen at 407.380.1553 or e-mail: bcohen@laserinstitute.org. Alphabetical order; Registered as of December 15.

> **Beijing Purple Light Laser Beijing University of Technology Chutian Laser** Coherent, Inc. Del Mar Photonics, Inc. Delphilaser **GE Global Research** GSI Group, Inc.

Huagong Laser Engineering Institute of Semiconductors CAS IPG Photonics Corporation Maohe Laser (Wuhan)

Natural Science Foundation of China Northrop Grumman Cutting Edge Optronics SPI Lasers

Swinburne Univ. of Technology **Unity-Prima (Shanghai) Zhejiang CHN-LASER Technology Co. LTD**

Micro, Nano & Ultrafast Fabrication Conference



Yongfeng Lu, Univ. of Nebraska-Lincoln Lincoln, NE, USA



Xiaoyan Zeng, Huazhong Univ. of Science & Technology Wuhan, People's Republic of China

New laser technologies for micro/nano/ultrafast fabrication and diagnosis continue to be the focus of academic research and industry applications. The explosion of new ideas in the photonics, material processing, microelectonics packaging, and biomedical fields has created a unique need for fabrication and diagnostics at micro/nanoscales using continuous wave, nanosecond, picosecond, and femotosecond lasers. The Laser Micro, Nano, and Ultrafast Fabrication Conference at PICALO 2008 is a global forum for engineers and scientists from a variety of industry segments and institutes to meet and discuss use of laser micro/nano/ultrafast fabrication and diagnosis as a key technology for various applications. Attendees will find innovative ideas and solutions for micro/ nano/ultrafast fabrication in opto- and microelectronics, electronics, microsystems, material processing and biomedical industries. This conference will highlight new and exciting achievements in structuring with highest precision using laser pulses from the nanosecond down to the pico- and femtosecond time regime. Special sessions are dedicated to fundamental science in laser-material interactions, near-field phenomena for nanoprocessing, laser microfabrication and micromachining, laser microwelding, laser-assisted device

fabrication, laser direct writing, ultrafast processes in materials processing, laser synthesis and sintering of nanoparticles, and lasers application in bio-engineering. In this way, we may highlight the newest developments and their promising perspectives. Outstanding researchers will give keynote and invited presentations in order to provide a deep insight into the current research work in these fields.

Program Committee:

Craig Arnold, Princeton Univ., Princeton, NJ, USA Dieter Baeuerle, Johannes-Kepler-Univ., Linz, Osterreich, Austria Jimin Chen, National Center of Laser Technology, Beijing Univ. of Technology, Beijing, People's Republic of China

Jan J. Dubowski, Univ. de Sherbrooke, Sherbrooke, QC, Canada

Bo Gu, GSI Group, Inc., Wilmington, MA, USA Erol Harvey, Swinburne Univ. of Technology, Melbourne, Australia

Wenhao Huang, Univ. of Science and Technology of China, Hefei, People's Republic of China

Lu Li, National Univ. of Singapore, Singapore

Xinbing Liu, Panasonic Boston Laboratory, Cambridge, MA, USA Eric Mazur, Harvard Univ., Cambridge, Massachusetts, USA Ashish Nath, IIT, Kharagpur, India

Tatsuo Okada, Kyushu Univ., Motooka, Fukuoka, Japan Andreas Ostendorf, Laser Zentrum Hannover e.V., Hannover, Germany

James Piper, Macquarie Univ., Sydney, Australia **Koji Sugioka,** RIKEN, The Institute of Physical and Chemical Research, Saitama, Japan

Hai-Lung Tsai, Univ. of Missouri-Rolla, Rolla, MO, USAKunihiko Washio, Paradigm Laser Research Ltd., Machida, Tokyo, Japan

Xianfan Xu, Purdue Univ., West Lafayette, IN, USA

Micro Session 1: Fundamental Science in Laser-Material Interactions Wednesday, April 16 • 1:30pm

Session Chair: Xianyan Zeng, Huazhong Univ. of Science & Technology, Wuhan, People's Republic of China

Fundamental Issues Concerning Material Removal by Laser Irradiation from Insulating Materials (Invited Paper).....(M101)
Tom Dickinson, Washington State Univ.

Processing of Polymer and Organic Materials using Tunable Ultrafast Mid-infrared Lasers (Invited Paper)(M102) Richard Haglund, Vanderbilt Univ.

Laser Micro-fabrication of Custom Micro-optics for Beam Brightness Enhancement of High Power Diode Lasers (Invited Paper).... (M104) D.R. Hall, H.J. Baker, R. McBride, E. Mendez, School of Engineering and Physical Sciences, Heriot-Watt Univ.

Micro Session 2: Near-Field Phenomena for Nanoprocessing Wednesday, April 16 • 3:10pm

Session Chair: Yongfeng Lu, Univ. of Nebraska - Lincoln, Lincoln, NE, USA

Nanoscale Laser Processing and Diagnostics (Invited Paper)... (M201) Costas Grigoropoulos, Univ. of California

High Transmission Nanoscale Ridge Apertures and Its Application in Laser-based Nanomanufacturing (Invited Paper)..... (M203) Xianfan Xu, Purdue Univ.

Sub-wavelength Laser Direct Write Patterning (Invited Paper)...(M204) Euan Mcleod, Craig B. Arnold, Princeton Univ.

Tuning the Near-field Focusing of Particle Lens for Surface Nanofabrication (M205) Zengbo Wang, Laser Processing Research Centre; Wei Guo, David

Zengbo Wang, Laser Processing Research Centre; Wei Guo, David Whitehead, Lin Li, Laser Processing Research Centre, School of Mechanical, Aerospace and Civil Engineering; Lukyanchuk Boris, Data Storage Institute; Zhu Liu, Corrosion and Protection Centre, School of Materials

Micro Session 3: Laser Microfabrication in Industry Thursday, April 17 • 9:00am

Session Chair: Hai-Lung Tsai, Univ. of Missouri-Rolla, Rolla, MO, USA

Progress in R&D on Ultrafast Laser Processing and Prospect of Industrial Applications (Invited Paper).....(M301)

Xinbing Liu, Panasonic Boston Lab.

Innovative Laser Technology for Semiconductor Manufacturing - Stealth Dicing (Invited Paper) (M302) Etsuji Ohmura, Osaka Univ.; Masayoshi Kumagai, Hideki Morita, Hamamatsu Photonics K.K.

Single Step Micro Laser Cladding of Nanophased Powders (M304) Henrik Mewes, Sonja Dudziak, Nils Weidlich, Oliver Meier, Laser Zentrum Hannover e.V.; Stefan Czerner, Microls

> Micro Session 4: Laser Assisted Device Fabrication Thursday, April 17 • 9:00am

Session Chair: Xinbing Liu, Panasonic Boston Laboratory, Cambridge, MA, USA

Experimental Micromachining Results using a UV Laser with the Laser Microjet®..................(M404)

John Stay, Synova SA

Micro Session 5: Laser Microwelding Thursday, April 17 • 10:40am

Session Chair: Koji Sugioka, RIKEN, Saitama, Japan

Microwelding Performance Comparison Between a Low Power (125W) Pulsed Nd:YAG Laser and a Low Power (200W) Single Mode Fiber Laser.....(M502)

Mohammed Naeem, GSI Group, Inc. - Laser Division

Development and Application of Miniaturized Scanners for Laser Beam Micro Welding(M503) Felix Schmitt, Fraunhofer ILT	Micro Session 9: Lasers in Bio-engineering Friday, April 18 • 9:00am			
Parameter Studies of Fibre Laser Micro-welding of SS316L using Taguchi Method(M504)	Session Chair: Jan J. Dubowski, Univ. de Sherbrooke, Sherbrooke, QC Canada			
Chan Chi Wai, H.C. Man, T.M. Yue, AMT Research Center, Dept. of ISE, The Hong Kong Poly Univ.	Optical-driven Nano Machines with Real-time Force Sensing and Biochemical IC Chip Family Fabricated by Two/Single Photon Micro Stereolithography (Invited Paper)(M901) Koji Ikuta, Nagoya Univ.			
Micro Session 6: Laser Direct Writing Thursday, April 17 • 10:40am	USP Laser Dissemination and Separation of Tissues (Invited Paper)(M902) Zhixiong Guo, Huan Huang, Xiaoliang Wang, Rutgers, The State Univ. of			
Session Chair: Kunihiko Washio, Paradigm Laser Research Ltd, Machida, Tokyo, Japan	New Jersey Laser Device for Elemental Determination in Human Skin (M904)			
Recent Progress of Femtosecond Laser Micro-nano Fabrication (Invited Paper) (M601) Wenhao Huang, USTC	Luis Ponce, CICATA-IPN			
0	Micro Session 10: Laser Micromachining Friday, April 18 • 10:40am			
Picosecond Lasers in Industrial Micromachining Applications (Invited Paper) (M602) Rainer Kling, Laser Zentrum Hannover e.V.	Session Chair: Li Lu, National Univ. of Singapore, Singapore			
Laser Direct-write using Air-drying Conductive Paste (Invited	Manufacturing of Shaped Holes in Multi-layer Plates by Laser-drilling			
Paper)				
Direct Fabrication of Micro Temperature Sensor Arrays by Laser Micro-cladding Functional Materials on Ceramic Substrates (M604) Cai Zhixiang, Li Xiangyou, Zeng Xiaoyan, Wuhan National Lab. for	für Lasertechnik, RWTH Practical Issues in Laser Micro/Nano Machining (M1002) Wenwu Zhang, Jeffrey Shaw, Brian Farrell, GE Global Research			
Optoelectronics	Laser-assisted-hot Embossing of Microstructures (M1003) Jens Holtkamp, Fraunhofer ILT			
Micro Session 7: Ultrafast Processes in Materials Processing Thursday, April 17 • 1:30pm	Laser Assisted Micro and Nano Replication (M1004) Qin Hu, William O'Neill, Institute for Manufacturing, Dept. of			
Session Chair: Wenhao Huang, Univ. of Science and Technology of China, Hefei, People's Republic of China	Engineering, Univ. of Cambridge			
	Micro Session 11: Laser Synthesis & Sintering of Nanoparticles			
Multiscale Modeling of Ultrafast Laser-material Interactions (Invited Paper)	Friday, April 18 • 1:30pm			
Lan Jiang, Beijing Institute of Technology; Hai-Lung Tsai, Univ. of Missouri-Rolla	Session Chair: Xianfan Xu, Purdue Univ., West Lafayette, IN, USA			
Missouri-Rolla Novel Aspects of Microprocessing by Ultrafast Lasers: From Electronic to Biological and Cultural Heritage Applications	Laser Fabrication of Nanoparticles and Crystals in Solution (Invited Paper)(M1101)			
Missouri-Rolla Novel Aspects of Microprocessing by Ultrafast Lasers: From Electronic to Biological and Cultural Heritage Applications (Invited Paper) (M702)	Laser Fabrication of Nanoparticles and Crystals in Solution (Invited Paper)			
Missouri-Rolla Novel Aspects of Microprocessing by Ultrafast Lasers: From Electronic to Biological and Cultural Heritage Applications	Laser Fabrication of Nanoparticles and Crystals in Solution (Invited Paper)			
Missouri-Rolla Novel Aspects of Microprocessing by Ultrafast Lasers: From Electronic to Biological and Cultural Heritage Applications (Invited Paper)	Laser Fabrication of Nanoparticles and Crystals in Solution (Invited Paper)			
Missouri-Rolla Novel Aspects of Microprocessing by Ultrafast Lasers: From Electronic to Biological and Cultural Heritage Applications (Invited Paper)	Laser Fabrication of Nanoparticles and Crystals in Solution (Invited Paper)			
Missouri-Rolla Novel Aspects of Microprocessing by Ultrafast Lasers: From Electronic to Biological and Cultural Heritage Applications (Invited Paper)	Laser Fabrication of Nanoparticles and Crystals in Solution (Invited Paper). (M1101) Hiroshi Masuhara, Osaka Univ. Fabrication of Nanomaterials by Laser Irradiation Process in Liquid Phase (Invited Paper). (M1102) Naoto Koshizaki, National Institute of Advanced Industrial Science and Technology Flash Lamp Curing of Nano-particulates for Passive Device Fabrication (Invited Paper) (M1103) James Sears, South Dakota School of Mines & Technology Fabrication of Micro-structured Components by Laser			
Missouri-Rolla Novel Aspects of Microprocessing by Ultrafast Lasers: From Electronic to Biological and Cultural Heritage Applications (Invited Paper)	Laser Fabrication of Nanoparticles and Crystals in Solution (Invited Paper)			
Missouri-Rolla Novel Aspects of Microprocessing by Ultrafast Lasers: From Electronic to Biological and Cultural Heritage Applications (Invited Paper)	Laser Fabrication of Nanoparticles and Crystals in Solution (Invited Paper)			
Missouri-Rolla Novel Aspects of Microprocessing by Ultrafast Lasers: From Electronic to Biological and Cultural Heritage Applications (Invited Paper)	Laser Fabrication of Nanoparticles and Crystals in Solution (Invited Paper). (M1101) Hiroshi Masuhara, Osaka Univ. Fabrication of Nanomaterials by Laser Irradiation Process in Liquid Phase (Invited Paper). (M1102) Naoto Koshizaki, National Institute of Advanced Industrial Science and Technology Flash Lamp Curing of Nano-particulates for Passive Device Fabrication (Invited Paper) (M1103) James Sears, South Dakota School of Mines & Technology Fabrication of Micro-structured Components by Laser Micro-deposition (M1104)			
Missouri-Rolla Novel Aspects of Microprocessing by Ultrafast Lasers: From Electronic to Biological and Cultural Heritage Applications (Invited Paper)	Laser Fabrication of Nanoparticles and Crystals in Solution (Invited Paper)			
Missouri-Rolla Novel Aspects of Microprocessing by Ultrafast Lasers: From Electronic to Biological and Cultural Heritage Applications (Invited Paper)	Laser Fabrication of Nanoparticles and Crystals in Solution (Invited Paper)			
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Missouri-Rolla Novel Aspects of Microprocessing by Ultrafast Lasers: From Electronic to Biological and Cultural Heritage Applications (Invited Paper)	Laser Fabrication of Nanoparticles and Crystals in Solution (Invited Paper)			
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Novel Aspects of Microprocessing by Ultrafast Lasers: From Electronic to Biological and Cultural Heritage Applications (Invited Paper)	Laser Fabrication of Nanoparticles and Crystals in Solution (Invited Paper)			

Laser Materials Processing Poster Presentation Gallery

TitutSudy	, April 17
Patent Analysis of Laser Cutting Technique (P101) Bingkun Xiang, Nanjing Univ. of Aeronautics and Astronautics	Repairing of Metal Components with Laser Cladding (P125) Qilin Deng, Shanghai Jiaotong Univ.
Effects of Rare Earth Oxide on the Nucleation of Carbide Particles in Laser Cladded MMCP Coating	New Development of Far Distance Coaxial Powder Feeding System. (P126) Yang Xichen, Yang Xichen, Laser Processing Center, Tianjin Polytechnic
Laser Beam Shaping and Surface Treatment of Ze41A-T5 Magnesium Alloy	Univ. Robust Sensing and Control of Direct Metal Deposition (P127) Lijun Song, Jyoti Mazumder, CLAIM, The Univ. of Michigan
R.K. Singh Raman, Monash Univ., Dept. of Mechanical Engineering; Darren Gerrard, Bruce Hinton, Defence Science and Technology Organization Study on the Pore Control of 5083 Aluminum Alloy by Dual-beam Laser Welding	Seam Tracking during Laser Beam Welding of Tailored Blanks with Vision Sensor
Kai Chen, Rui Huang, Rongshi Xiao, Xudong Zhao, Song Zhang, Beijing Univ. of Technology Microstructure of Laser Joints of Az31B Wrought Magnesium Alloy(P105) Shan Ji-guo, Lei Xiang, Tan Wen-Da, Chen Wu-Zhu, Dept. of Mechanical	High-power Laser Processing System for 3D Cutting and Welding of Automotive Panels
Engineering, Tsinghua Univ. Study on the Surface Treatment for Controlling the Aluminum-lithium Alloy Weld Porosity of Laser Welding (P106) Yang Jing, Chen Li, Gong Shuili, BAMTRI; Li Xiaoyan, BJUT	Electron Concentration and Ionization Rate Study of Discharge for Rf Excited Diffusively Cool All Metal Slab Waveguide Co2 Laser (P130) Li Zhiming, Dept. of Engineering Optics, School of Information Science and Technology
Single Mode Fibre Laser Welding of Dissimilar Aerospace Alloys(P107) Hui-Chi Chen, Andrew Pinkerton, Ziu Liu, Lin Li, The Univ. of Manchester Laser Ablation of Al2O3 Ceramic in NaOH Medium(P108)	Airborne Laser Hydrography and Visual Analysis of Full-waveform Airborne Laser Scanner Data(P131) Abhishek Dodiyal, Anand Kumar, Pradeep M.Omanakuttan, HCE; Mervin Praison, Hindustan College
Shao Feng, Anhui Institute of Architecture & Industry Investigation in Laser Colorful Marking in Stainless Steel by Pulsed Fiber Laser	Laser Cladding Layer Height Automatic Detecting Control (P132) Huilai Sun, School of Mechanical and Electronic Engineering, Tianjin Polytechnic Univ.
Engineering, Beijing Univ. of Technology Laser Sintering of (K0.5Na0.5Nbo3)-Litao3 Lead-free Ceramics with	Fiber Laser Technology Latest Development(P133) Jun Shao, Institute of Laser Engineering, Beijing Univ. of Technology
Novel Piezoelectric Properties	Research on Multi-purpose Laser Integrated Machine for Auto Clutch(P134) Zhengfeng Yan, Wuhan Univ. of Technology
Laser Cladding of Ti-Base Composite Coatings on Ti-6Al-4V Substrate (P111) Wei-fu Wang, Maocai Wang, Fengjiu Sun, Northeastern Univ.	Growth and Dielectric Properties of Ta2O5 Single Crystal Fibers(P135) Yijian Jiang, Institiute of Laser Engineering, Beijing Univ. of Technology
Application and Performance Evaluation for the New Material in the Industrial SFF System using a SLS Process(P112) Dong Soo Kim, Sung Woo Bae, Chung Hwan Kim, Byung Oh Choi, Korea Institute Machinery & Materials Venus Kill Bang, Lious horsteel Co. Ltd.	Finite Element Simulation for Temperature Field in Nd:YAG Laser-TIG Hybrid Welding of 5A06 Aluminum Alloy(P136) Xian-feng Shen, Institute of Machinery Manufacturing Technology
Institute Machinery & Materials; Young Kil Bang, Lionchemtech Co., Ltd. Experimental Research on Functional Graded Cladding Layer of Titanium Alloy(P113) Fangyou Hu, NAEA	Researches on Wear Performance of 40Cr Steel Strengthened by Laser Cladding
The Rapid Solidification Characteristics of Ni-Based Alloy Fabricated by Laser Engineered Net Shaping (P114) Fei Qunxing, BAMTRI	Numerical Optimization of Surface Residual Stresses Induced by Laser Peening using Taguchi Method (P138) Qing Sun, Jiangsu Univ.
The Research on the Parameter Thresholds of Titanium Alloy Laser Welding (P115) Chen Li, BAMTRI	Numerical Simulation and Response Optimizer Design of Strengthening Effects Induced by Laser Shock Peening (P139) Shu Huang, Jian-Zhong Zhou, Jiangsu Univ.
An Experimental Study on Welding Parameters for Laser Welding of NiTi Shape Memory Alloys (P116)	Nitridation of Titanium by the Laser and Plasma Mixing Method (P140) Fengjiu Sun, Northeastern Univ. Friction and Wear Characteristics of Nano-solid Lubrication Coating of
Wang Wei, Aviation Univ. of Air Force; Chang Chun, BAMTRI Effect of Beam Factors on Beam-focusing Characters and Laser Penetration Welding(P117)	Laser Cladding
Hong Chen, Institute of Laser Engineering, Beijing Univ. of Technology Spectroscopic Investigation of Laser-induced Plasma in Co2 Laser Welding Aluminum Alloy(P118)	Microstructural Characterization of Nd:YAG Laser-welded 12vol.% SiC Particulate-reinforced Magnesium Alloy Composite (P142) A.H. Wang, Huazhong Univ. of Science and Technology
Junfeng Qi, Beijing Univ. of Technology Study on Laser Repair Welding to Brazing Bead of 6063 Aluminum	Electroless Nickle Plating on Nano-HBN Particles for Producing Self-
Alloy(P119) Zhao Xudong, Chen Kai, Xiao Rong-Shi, Beijing Univ. of Technology	lubricating Coatings by Laser Cladding(P143) A.H. Wang, Huazhong Univ. of Science and Technology Microstructure and Properties of Laser Remelted Ni-based Alloy
Experimental Study on the Quality of Material Surface Applied Laser-chemical Combined Etching (P120) Yao Yansheng, Anhui Institute of Architecture and Industry	Self-lubricating HVOF Spraying Coating(P144) A.H. Wang, Huazhong Univ. of Science and Technology
Technological Study of Oxygen Aided Laser Cutting Silicon Steel(P121) Hong Lei, Shanghai Maritime Univ.	Experimental Investigation Laser Twin Spot Nd:YAG Laser Welding of Aluminum Alloys (P145) Yao Wei, BAMTRI
Investigation on Nd:YAG Laser-TIG Hybrid Welding with Filler Wire	Analysis on the Effect of Weld Appearance Induced by Order of Heat Source during Laser-plasma Arc Hybrid Welding Al-Li Alloy (P146) Zhining Li, Artillery Engineering Dept., Ordnance Engineering College

Micro, Nano & Ultrafast Fabrication Poster Presentation Gallery Friday, April 18

Generation of the Nickel Nanoparticles by CW Laser Ablation in Liquid	Micro Processing with High Repetition Rate Pulsed Fibre Lasers (P220) Jack Gabzdyl, Tony Hoult, SPI Lasers				
Sohaib Khan, Yudie Yuan, Zhu Liu, CPC, The Univ. of Manchester; Amin Abdolvand, Philip Crouse, Lin Li, Marc Schmidt, LPRC, The Univ. of Manchester	State of the Art Microfabrication with Excimer Lasers (P221) Ralph Delmdahl, Coherent GmbH; Burkhard Fechner, Coherent GmbH				
Localised Laser Joining of Glass to Silicon with BCB Intermediate	Micro Welding of Thin Foil with an Elliptical Beam of Direct Diode				
Layer	Lasers				
Microdrilling of the Cupreous Probe by UV DPSS Laser (P203) Zhai Libin, Chen Jimin, Jiang Maohua, Wang Xubao, Yu Zhensheng, Zong Xiaojun, National Center of Laser Technology	Derivation of Optimal Processing Parameters for Conduction Mode Laser Beam Welds by Simulation (P223) Achim Mahrle, TU Dresden / IOF - LOT; Eckhard Beyer, Fraunhofer IWS				
Nonequilibrium Synthesis of Ni-Al-Si Alloys by Laser Processing(P204)	Study of the Laser Assisted Vapor Condensation Method for Generating Metallic Nano-particles (P224) Jen-Hong Jang, Jehnming Lin, National Cheng Kung Univ.				
Yufeng Zheng, Yaoning Sun, Ding Fan, Min Zheng, Jianbin Zhang, Lanzhou Univ. of Technology	Development of Excimer Laser and Its Applications in Our Lab (P225) Yao Liying, Institute of Laser Technology, Beijing Univ. of Technology				
A Novel Soft-lithography based Polymeric Multimode Laser Power Splitter (P205) Rubing Shao, Shu Li, Qiao Lin, Wei Ni, Xing K. Wu, Zhejiang Univ.	Laser Range Finder Base on FM Ranging Principles (P228) Yang Jin, Academy of Equipment Command & Technology				
Joining of Thin Glass with Semiconductors by Ultra-fast High-repetition Laser Welding	Temperature Field Simulation of Ta2O5 Ceramics by CO2 Laser Irradiation (P229) Xinyu Du, Beijing Univ. of Technology				
Ingomar Kelbassa, Lehrstuhl für Lasertechnik, RWTH Aachen A Study of Laser Etching and Cutting PCB Boards by 355Nm DPSS UV	Laser Cladding of Az91D Magnesium Alloy with Ni-Si-Mg (P230) Ding Fan, Jianbin Zhang, Yufeng Zheng, Qiang Li, Lanzhou Univ. of				
Laser	Technology Characterization of Laser Cladding Calcium Phosphate Coatings on Titanium Substrate(P231) Xiukun Li, Min Zheng, Ding Fan, Jianbin Zhang, Lanzhou Univ. of				
Double-pulse Laser Drilling with Different Pulse Energy Distributions	Technology				
Technology; Andreas Michalowski, Friedrich Dausinger, Institut für Strahlwerkzeuge	Defects Research of ZnO Crystal with Femtosecond Laser (P232) Sun Xiaohui, College of Fundamental Studies, Shanghai Univ. of Engineering Science				
Oxidation Behavior of Laser Cladded Ni-Si-Ti-C Coatings at 1100°C	A Novel Multi-functional Fiber Grating Sensor with Self-demodulation and Discrimination Capabilities (P233) Erjun Liang, Zhengzhou Univ.				
Tool Steel Laser Surface Modification with TiC/TiN(P210)	Research of Digital Controlled Laser Die-cutting Technology (P234) Meng Wang, LiNeng Laser				
M.A. Montealegre, G. Castro, J.L. Arias, A. Fernández-Vicente, J. Vázquez, AIMEN	The Influence of the Shielding Gas on Process Properties during Laser Welding(P235)				
Large Area Nanopatterning of Silicon Surface by Chemical Assisted Laser Processing using Near-field Enhancement by Particle-lens	Duan Aiqin, BAMTRI				
Arrays	The Research on the Joint Microstructure and Properties of Dual Spot Laser Welding of 5A90 Al-Li Alloy (P236) Jing Yangming, BAMTRI				
Univ. of Manchester The Investigation of Cutting Polycrystalline Diamond using 355nm UV	Research on Laser Transmission Welding PVC(P237) Huixia Liu, Jiangsu Univ.				
Pulse Laser	Millisecond Pulse Laser Bending of Silicon(P238) Dongjiang Wu, Dalian Univ. of Technology				
of Laser Technology; Sun Chunyu, Beijing Beidou Diamond Company Femtosecond Laser Pulses Induced Nanostructures on ZnO in	Optical Property of Thermal Barrier Coating at High Temperature(P239) Geunsik Lim, CREOL, Univ. of Central Florida				
Different Ablation Atmospheres (P215) Xiaodong Guo, Ruxin Li, Shanghai Institute of Optics and Fine Mechanics; Bingkun Yu, Shanghai Univ.	CO2 Laser Produced Sn Plasma for EUV Lithography (P240) Akira Endo, EUVA				
Formation of Micro-nano Structure by Laser Deposition and Dealloying of Copper Alloy Layer on Macro-component Surface (P216) Yide Kan, Wenjin Liu, Minlin Zhong, Tsinghua Univ.	Numerical Simulation and Ecperiment Study on Pulse Laser Surface Micro-tecturing in Carbon Tool Steel (P241) Huixia Liu, Shengjun Yang, Xiao Wang, Jiangsu Univ.				
Drilling of Microvias with Frequency Doubled Nd:YAG Laser (P217) Chong Zhang, Aravinda Kar, CREOL, Univ. of Central Florida; Nathaniel Quick, AppliCote Associates, LLC	Water Assisted Laser Milling of Partially Sintered Ti Powder for Rapid Manufacture				
Study on the Angular Deformation of Laser Cladding on Thin Plate	Crack Controlling of Nano-composite Coating with Ni-Al2O3 by Pulsed Nd:YAG Laser Cladding(P243)				
Zheng Xiong, Wuhan National Lab. for Optoelectronics, Huazhong Univ. of Science and Technology; Xiaoyan Zeng, Qianwu Hu, Huazhong Univ.	Qunli Zhang, Jianhua Yao, Yi Pan, Zhejiang Univ.				
of Science and Technology Surface Roughness Analysis and Improvement of PMMA-based Micro-	Micro Cutting of Madin-darby Canine Kidney (MDCK) Cell using Femtosecond Laser				
fluidic Chip Chamber by Co2 Laser Cutting (P219) Huang Yongguang, Liu Shibing, Beijing Univ. of Technology	Science and Technology of China				

General Information

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3 Qian Men East Street

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Laser Industry Vendor Reception & TableTop Display • Thursday, April 17

The Laser Industry Vendor Program gives vendors and conference attendees the opportunity to discuss equipment and applications in a relaxed setting. After completion of the technical sessions, share refreshments and product ideas with your colleagues and suppliers! Limited space is still available! For more information on participating as a vendor, contact Beth Cohen at +407.380.1553 or e-mail: picalo@laserinstitute.org.

Who should attend PICALO?

Anyone interested in lasers and materials processing from the basic understanding of the interaction between a laser beam and a material, to those interested in how a process can be integrated and optimized for an application. The organizing committee's goal for PICALO is to bring both academic and industry people together who may benefit from laser technology. This includes researchers and end-users as well as engineers and technicians engaged in developing laser technology.



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PICALO 2008 Advance Program

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